



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-06-09
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS1H100AF	7NC5*Z24P83V	A	ZA41	2020-06-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	35	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		



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Package Designator	Size	Nbr of instances	Shape	
SOJ	4.14,2.76,1.94	2	J bend	
Comment	Package: SMA Flat 2 Leads No exposed pad			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	die	200
Lead	2.39	soft solder	68200

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.39	soft solder	68200
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.39	soft solder	925194

Material Composition Declaration :						Mfr Item Name	7NCS*Z24P83V					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.581	mg	supplier	die	Silicon (Si)	7440-21-3		0.548	mg	943200	15656
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	6885	114
				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	5164	86
				supplier	passivation	Nickel (Ni)	7440-02-0		0.003	mg	5164	86
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1721	29
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1721	29
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	6885	114
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1721	29
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.004	mg	6885	114
				supplier	polymer die coating	Durimide	Proprietary		0.012	mg	20654	343
Leadframe & Clip	M-004 Copper and its alloys	15.288	mg	supplier	alloy	Copper (Cu)	7440-50-8		15.265	mg	998496	436143
				supplier	alloy	Iron (Fe)	7439-89-6		0.018	mg	1177	514
				supplier	alloy	Phosphorus (P)	7723-14-0		0.005	mg	327	143
Soft solder	Solder	2.580	mg	supplier	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.387	mg	925194	68200
				supplier	soft solder	Tin (Sn)	7440-31-5		0.129	mg	50000	3686
				supplier	soft solder	Silver (Ag)	7440-22-4		0.064	mg	24806	1829
Encapsulation	M-011 Other inorganic materials	15.921	mg	supplier	mold compound	Silica , amorphous,fused	60676-86-0		12.737	mg	800012	363914
				supplier	mold compound	Epoxy resin propietare,resin unknow	29690-82-2		2.149	mg	134979	61399
				supplier	mold compound	Benzophenone teracarboxylic anhydride	2421-28-5		0.159	mg	9987	4543
				supplier	mold compound	Silica, quartz	14808-60-7		0.717	mg	45035	20486
				supplier	mold compound	Carbon black	1333-86-4		0.159	mg	9987	4543
Connection coating	Solder	0.630	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.630	mg	1000000	18000